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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	33MHz
Connectivity	EBI/EMI, UART/USART
Peripherals	-
Number of I/O	24
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	236 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z86c9333vsc

PIN DESCRIPTION

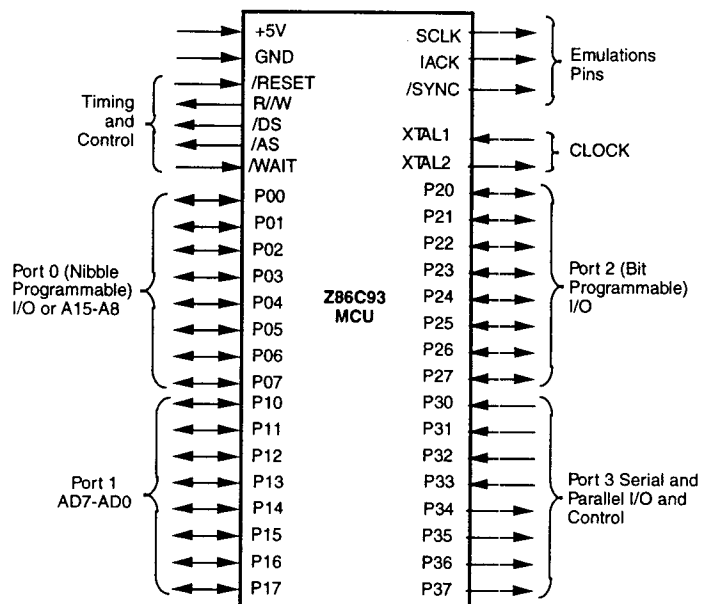


Figure 2. Pin Functions

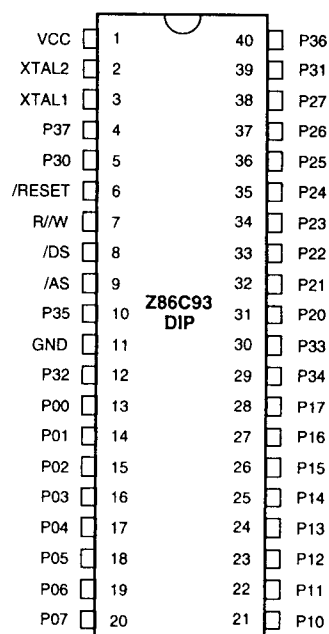


Figure 3. 40-Pin DIP

Table 1. 40-Pin DIP Pin Identification

Pin #	Symbol	Function	Direction
1	V _{CC}	Power Supply	Input
2	XTAL1	Crystal, Oscillator Clock	Input
3	XTAL2	Crystal, Oscillator Clock	Output
4	P37	Port 3 pin 7	Output
5	P30	Port 3 pin 0	Input
6	/RESET	Reset	Input
7	R/W	Read/Write	Output
8	/DS	Data Strobe	Output
9	/AS	Address Strobe	Output
10	P35	Port 3 pin 5	Output
11	GND	Ground, GND	Input
12	P32	Port 3 pin 2	Input
13-20	P00-P07	Port 0 pin 0,1,2,3,4,5,6,7	In/Output
21-28	P10-P17	Port 1 pin 0,1,2,3,4,5,6,7	In/Output
29	P34	Port 3 pin 4	Output
30	P33	Port 3 pin 3	Input
31-38	P20-P27	Port 2 pin 0,1,2,3,4,5,6,7	In/Output
39	P31	Port 3 pin 1	Input
40	P36	Port 3 pin 6	Output

PIN DESCRIPTION (Continued)

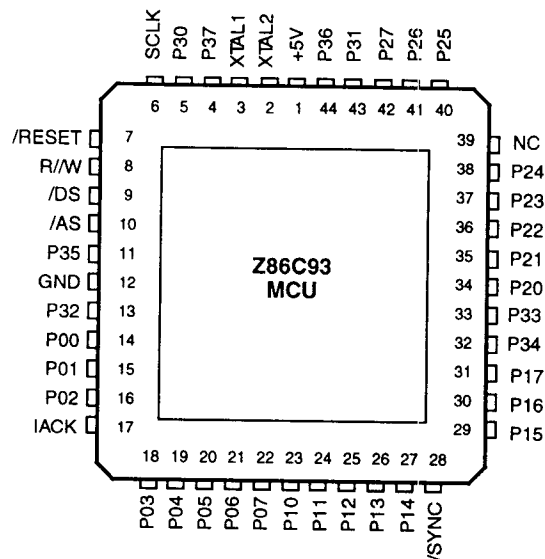


Figure 4. 44-Pin PLCC

Table 2. 44-Pin PLCC Pin Identification

No	Symbol	Function	Direction
1	V _{cc}	Power Supply	Input
2	XTAL2	Crystal, Osc. Clock	Output
3	XTAL1	Crystal, Osc. Clock	Input
4	P37	Port 3 pin 7	Output
5	P30	Port 3 pin 0	Input
6	SCLK	System Clock	Output
7	/RESET	Reset	Input
8	R/W	Read/Write	Output
9	/DS	Data Strobe	Output
10	/AS	Address Strobe	Output
11	P35	Port 3 pin 5	Output
12	GND	Ground GND	Input
13	P32	Port 3 pin 2	Input

No	Symbol	Function	Direction
14-16	P00-P02	Port 0 pin 0,1,2	In/Output
17	IACK	Int. Acknowledge	Output
18-22	P03-P07	Port 0 pin 3,4,5,6,7	In/Output
23-27	P10-P14	Port 1 pin 0,1,2,3,4	In/Output
28	/SYNC	Synchronize Pin	Output
29-31	P15-P17	Port 1 pin 5,6,7	In/Output
32	F34	Port 3 pin 4	Output
33	F33	Port 3 pin 3	Input
34-38	P20-P24	Port 2 pin 0,1,2,3,4	In/Output
39	N/C	Not Connected (20 MHz)	Input
	/WAIT	WAIT (25 or 33 MHz)	Input
40-42	P25-P27	Port 2 pin 5,6,7	In/Output
43	F31	Port 3 pin 1	Input
44	F36	Port 3 pin 6	Output

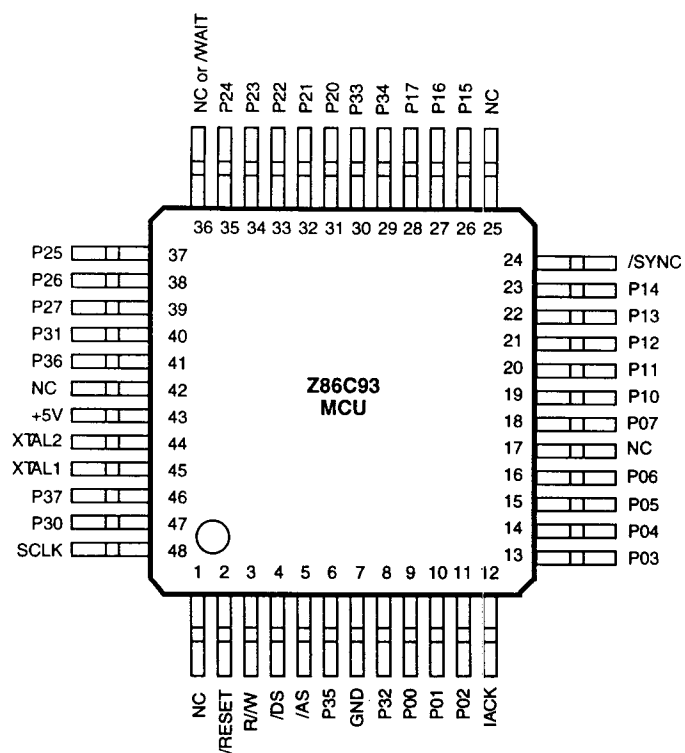


Figure 6. 48-Pin VQFP Package

Table 4. 48-Pin VQFP Pin Identification

No	Symbol	Function	Direction	No	Symbol	Function	Direction
1	N/C	Not Connected	Input	25	N/C	Not Connected	Input
2	/RESET	Reset	Input	26-28	P15-P17	Port 1 pin 5,6,7	In/Output
3	R/W	Read/Write	Output	29	F34	Port 3 pin 4	Output
4	/DS	Data Strobe	Output	30	F33	Port 3 pin 33	Input
5	/AS	Address Strobe	Output	31-35	P20-P24	Port 2 pin 0,1,2,3,4	In/Output
6	P35	Port 3 pin 5	Input	36	N/C	Not Connected (20 MHz)	Input
7	GND	Ground GND	Input		/WAIT	WAIT (25 or 33 MHz)	Input
8	P32	Port 3 pin 2	Input	37-39	P25-P27	Port 2 pin 5,6,7	In/Output
9-11	P00-P02	Port 0 pin 3,4,5,6	In/Output	40	F31	Port 3 pin 1	Input
12	IACK	Int. Acknowledge	Output	41	P36	Port 3 pin 6	Output
13-16	P03-P06	Port 0 pin 3,4,5,6	In/Output	42	N/C	Not Connected	Input
17	N/C	Not Connected	Input	43	V _{cc}	Power Supply	Input
18	P07	Port 0 pin 7	In/Output	44	XTAL2	Crystal, Osc. Clock	Output
19-23	P10-P14	Port 1 pin 0,1,2,3,4	In/Output	45	XTAL1	Crystal, Osc. Clock	Input
24	/SYNC	Synchronize Pin	Output	46	P37	Port 3 pin 7	Output
				47	P30	Port 3 pin 0	Input
				48	SCLK	System Clock	Output

Port 3 P30-P37. Port 3 is an 8-bit, TTL compatible four fixed input and four fixed output ports. These eight I/O lines have four fixed (P30-P33) input and four fixed (P34-P37) output

ports. Port 3 pins P30 and P37 when used as serial I/O, are programmed as serial in and serial out, respectively (Figure 10 and Table 5).

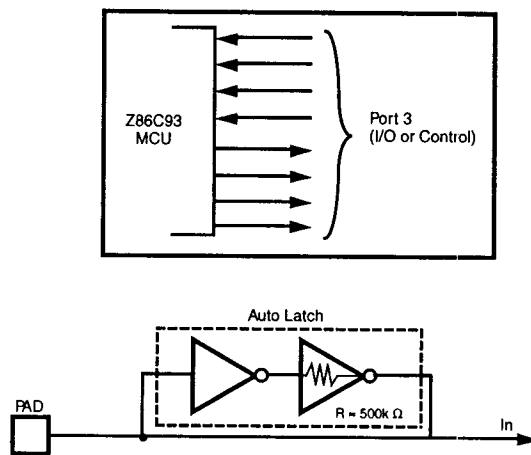


Figure 10. Port 3 Configuration

Table 5. Port 3 Pin Assignments

Pin #	I/O	CTC1	Int.	P0HS	P2HS	UART	Ext.
P30	In	T_{IN}	IRQ3	D/R	D/R	Serial In	
P31	In		IRQ2				
P32	In		IRQ0				
P33	In		IRQ1				
P34	Out	T_{OUT}		R/D	R/D	Serial Out	DM
P35	Out						
P36	Out						
P37	Out						

Port 3 is configured under software control to provide the following control functions: handshake for Ports 0 and 2 (/DAV and RDY); four external interrupt request signals (IRQ0-IRQ3); timer input and output signals (T_{IN} and T_{OUT}), and Data Memory Select (/DM).

Port 3 lines P30 and P37 can be programmed as serial I/O lines for full-duplex serial asynchronous receiver/transmitter operation. The bit rate is controlled by the Counter/Timer 0.

The Z86C93 automatically adds a start bit and two stop bits to transmitted data (Figure 10). Odd parity is also available as an option. Eight data bits are always transmitted,

regardless of parity selection. If parity is enabled, the eighth bit is the odd parity bit. An interrupt request (IRQ4) is generated on all transmitted characters.

Received data must have a start bit, eight data bits and at least one stop bit. If parity is on, bit 7 of the received data is replaced by a parity error flag. Received characters generate the IRQ3 interrupt request.

The Auto Latch on Port 3 puts a valid CMOS level on all CMOS inputs that are not externally driven. Whether this level is zero or one, cannot be determined. A valid CMOS level rather than a floating node reduces excessive supply current flow in the input buffer.



Figure 13. Register File

FUNCTIONAL DESCRIPTION

This section breaks down the Z86C93 into its main functional parts.

Multiply/Divide Unit

The Multiply/Divide unit describes the basic features, implementation details of the interface between the Z8 and the multiply/divide unit.

Basic features:

- 16-bit by 16-bit multiply with 32-bit product
- 32-bit by 16-bit divide with 16-bit quotient and 16-bit remainder
- Unsigned integer data format
- Simple interface to Z8

Interface to Z8. The following is a brief description of the register mapping in the multiply/divide unit and its interface to the Z8 (Figure 16).

The multiply/divide unit is interfaced like a peripheral. The only addressing mode available with the peripheral interface is register addressing. In other words, all of the operands are in the respective registers before a multiplication/division can start.

Register mapping. The registers used in the multiply/divide unit are mapped onto the expanded register file in Bank E. The exact register locations used are shown below.

REGISTER	ADDRESS
MREG0	(E) 00
MREG1	(E) 01
MREG2	(E) 02
MREG3	(E) 03
MREG4	(E) 04
MREG5	(E) 05
MDCON	(E) 06
GPR	(E) 14
GPR	(E) 15

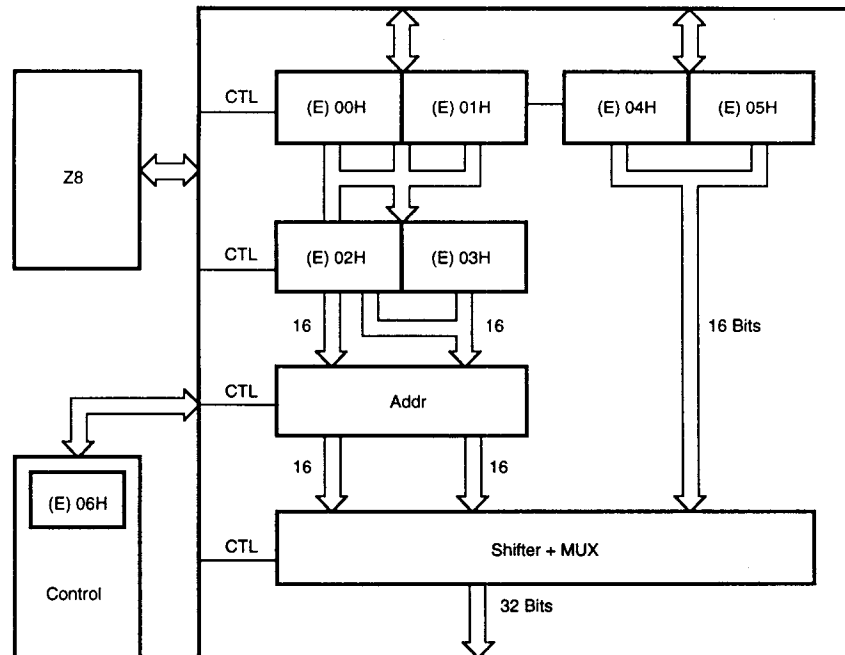


Figure 16. Multiply/Divide Unit Block Diagram

Interrupts

The Z86C93 has six different interrupts from nine different sources. The interrupts are maskable and prioritized. The nine sources are divided as follow: four sources are claimed by Port 3 lines P30-P33, one in Serial Out, one in Serial In, and three in the counter/timers. The Interrupt Mask Register globally or individually enables or disables the six interrupt requests. When more than one interrupt is pending, priorities are resolved by a programmable priority encoder that is controlled by the Interrupt Priority register. All Z86C93 interrupts are vectored through locations in the program memory. When an interrupt machine cycle is activated an interrupt request is granted. Thus, this disables all of the subsequent interrupts, save the Program Counter and Status Flags, and then branches to the program memory vector location reserved for that interrupt. This memory location and the next byte contain the 16-bit address of the interrupt service routine for that particular interrupt request.

To accommodate polled interrupt systems, interrupt inputs are masked and the Interrupt Request register is polled to determine which of the interrupt requests need service. Software initiated interrupts are supported by setting the appropriate bit in the Interrupt Request Register (IRQ).

Internal interrupt requests are sampled on the falling edge of the last cycle of every instruction. The interrupt request must be valid 5TpC before the falling edge of the last clock cycle of the currently executing instruction.

When the device samples a valid interrupt request, the next 48 (external) clock cycles are used to prioritize the interrupt, and push the two PC bytes and the FLAG register on the stack. The following nine cycles are used to fetch the interrupt vector from external memory. The first byte of the interrupt service routine is fetched beginning on the 58th TpC cycle following the internal sample point, which corresponds to the 63rd TpC cycle following the external interrupt sample point.

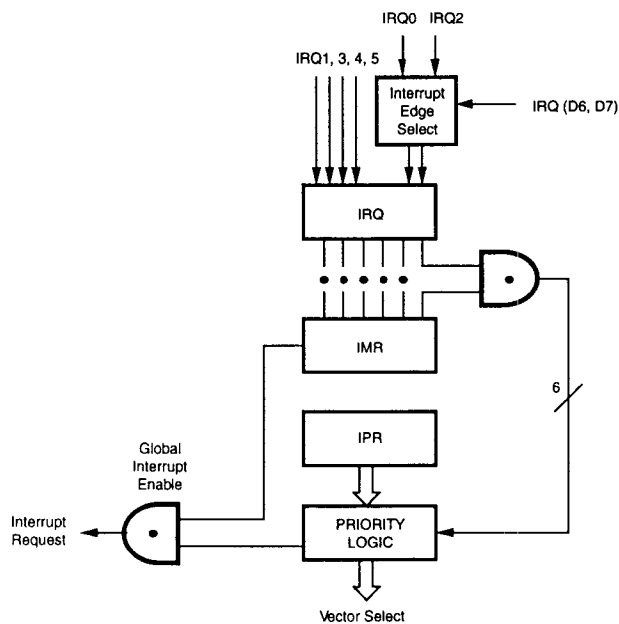


Figure 21. Interrupt Block Diagram

Power Down Modes

HALT. Turns off the internal CPU clock but not the XTAL oscillation. The counter/timers and the external interrupts IRQ0, IRQ1, IRQ2 and IRQ3 remain active. The devices are recovered by interrupts, either externally or internally generated. During HALT mode, /DS, /AS and R/W are HIGH. The outputs retain their preview value, and the inputs are floating.

STOP. This instruction turns off the internal clock and external crystal oscillation and reduces the standby current to 10 μ A or less. The STOP mode is terminated by a /RESET, which causes the processor to restart the application program at address 000CH.

In order to enter STOP (or HALT) mode, it is necessary to first flush the instruction pipeline to avoid suspending execution in mid-instruction. To do this, the user executes a NOP (opcode=OFFH) immediately before the appropriate sleep instruction, i.e.:

```
FF NOP ; clear the pipeline
6F STOP ; enter STOP mode
or
FF NOP ; clear the pipeline
7F HALT ; enter HALT mode
```

ABSOLUTE MAXIMUM RATINGS

Symbol	Description	Min	Max	Units
V_{CC}	Supply Voltage*	-0.3	+7.0	V
T_{STG}	Storage Temp	-65	+150	C
T_A	Oper Ambient Temp	†	†	C

* Voltages on all pins with respect to GND.

† See Ordering Information

Stress greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period may affect device reliability.

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to GND. Positive current flows into the referenced pin Test Load Diagram (Figure 23).

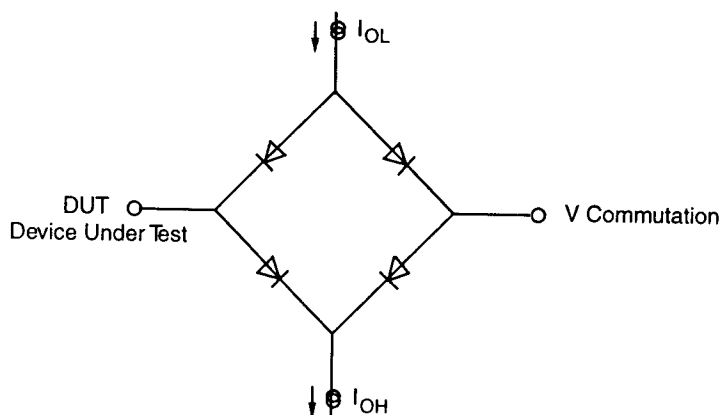


Figure 23. Test Load Diagram

DC ELECTRICAL CHARACTERISTICS

$V_{CC} = 5.0V \pm 10\%$

Sym	Parameter	$T_A = 0^\circ\text{C to } +70^\circ\text{C}$		Typical at 25°C	Units	Conditions
		Min	Max			
	Max Input Voltage		7		V	$I_{IN} = 250 \mu\text{A}$
V_{CH}	Clock Input High Voltage	3.8	V_{CC}		V	Driven by External Clock Generator
V_{CL}	Clock Input Low Voltage	-0.03	0.8		V	Driven by External Clock Generator
V_{IH}	Input High Voltage	2.0	V_{CC}		V	
V_{IL}	Input Low Voltage	-0.3	0.8		V	
V_{OH}	Output High Voltage	2.4			V	$I_{OH} = -2.0 \text{ mA}$
V_{OH}	Output High Voltage	$V_{CC} - 100\text{mV}$			V	$I_{OH} = -100 \mu\text{A}$
V_{OL}	Output Low Voltage		0.4		V	$I_{OL} = +5 \text{ mA}$
V_{RH}	Reset Input High Voltage	3.8	V_{CC}		V	
V_{RL}	Reset Input Low Voltage	-0.03	0.8		V	
I_{IL}	Input Leakage	-2	2		μA	Test at 0V, V_{CC}
I_{OL}	Output Leakage	-2	2		μA	Test at 0V, V_{CC}
I_{IR}	Reset Input Current		-80		μA	$V_{RL} = 0V$
I_{CC}	Supply Current		55	35	mA	@ 33 MHz [1]
			40	25	mA	@ 25 MHz [1]
			30	20	mA	@ 20 MHz [1]
I_{CC1}	Standby Current (HALT Mode)		15	9	mA	HALT Mode $V_{IN} = 0V$, V_{CC} @ 25 MHz [1]
			20	15		HALT Mode $V_{IN} = 0V$, V_{CC} @ 33 MHz [1]
			12	7	mA	HALT Mode $V_{IN} = 0V$, V_{CC} @ 20 MHz [1]
I_{CC2}	Standby Current (STOP Mode)		10	1	μA	STOP Mode $V_{IN} = 0V$, V_{CC} [1]
I_{AL}	Auto Latch Current	-16	16	5	μA	

Note:

[1] All inputs driven to 0V, or V_{CC} and outputs floating.

AC CHARACTERISTICS

External I/O or Memory Read/Write Timing Diagram

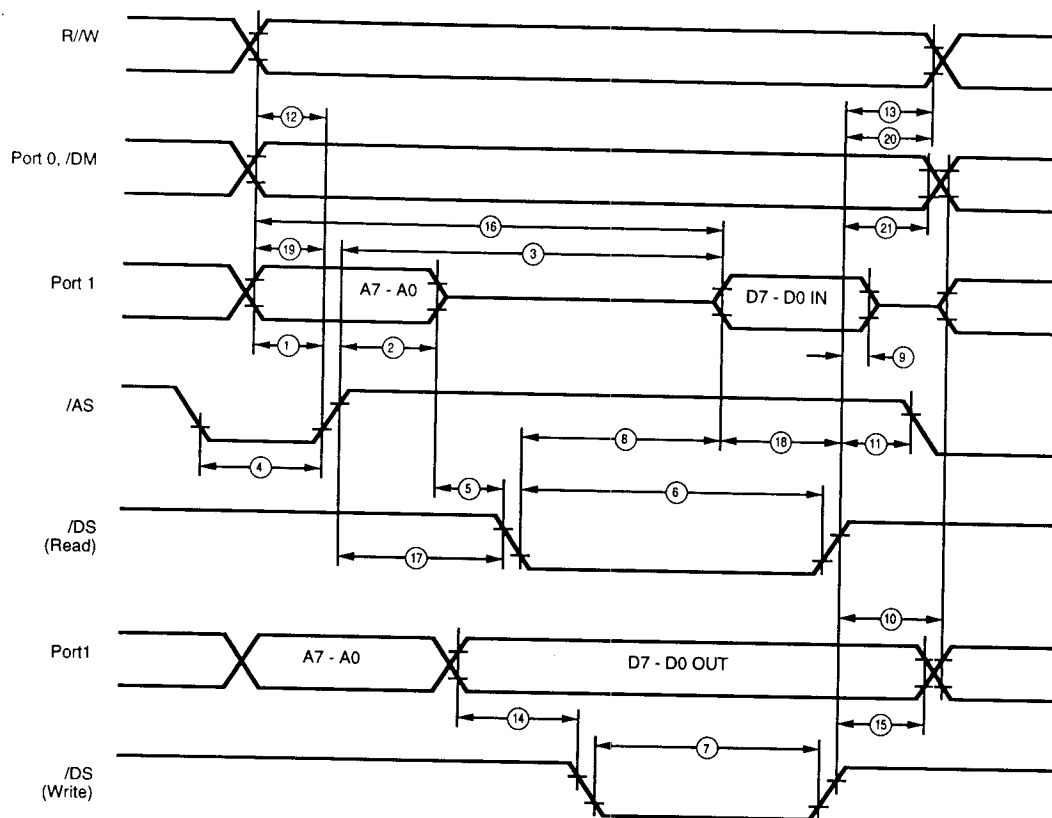


Figure 24. External I/O or Memory Read/Write Timing

AC CHARACTERISTICS

External I/O or Memory Read and Write; DSR/DSW; WAIT Timing Table

No	Sym	Parameter	T _A = 0°C to +70°C						Typical V _{cc} =5.0V @ 25°C	Units
			33 MHz		25 MHz		20 MHz			
			Min	Max	Min	Max	Min	Max		
1	TdA(AS)	Address Valid To /AS Rise Delay	13		22		26			ns
2	TdAS(A)	/AS Rise To Address Hold Time	20		25		28			ns
3	TdAS(DI)	/AS Rise Data In Req'd Valid Delay		90		130		160		ns
4	TwAS	/AS Low Width	20		28		36			ns
5	TdAZ(DSR)	Address Float To /DS (Read)	0		0		0			ns
6	TwDSR	/DS (Read) Low Width	65		100		130			ns
7	TwDSW	/DS (Write) Low Width	40		65		75			ns
8	TdDSR(DI)	/DS (Read) To Data In Req'd Valid Delay		30		78		100		ns
9	ThDSR(DI)	/DS Rise (Read) to Data In Hold Time	0		0		0			ns
10	TdDS(A)	/DS Rise To Address Active Delay	25		34		40			ns
11	TdDS(AS)	/DS Rise To /AS Delay	16		30		36			ns
12	TdR/W(AS)	R/W To /AS Rise Delay	12		26		32			ns
13	TdDS(R/W)	/DS Rise To R/W Valid Delay	12		30		36			ns
14	TdDO(DSW)	Data Out To /DS (Write) Delay	12		34		40			ns
15	ThDSW(DO)	/DS Rise (Write) To Data Out Hold Time	12		34		40			ns
16	TdA(DI)	Address To Data In Req'd Valid Delay		110		160		200		ns
17	TdAS(DSR)	/AS Rise To /DS (Read) Delay	20		40		48			ns
18	TaDI(DSR)	Data In Set-up Time To /DS Rise Read	16		30		36			ns
19	TdDM(AS)	/DM To /AS Rise Delay	10		22		26			ns
20	TdDS(DM)	/DS Rise To /DM Valid Delay							34*	ns
21	ThDS(A)	/DS Rise To Address Valid Hold Time							34*	ns
22	TdXT(SCR)	XTAL Falling to SCLK Rising							20*	ns
23	TdXT(SCF)	XTAL Falling to SCLK Falling							23*	ns
24	TdXT(DSRF)	XTAL Falling to /DS Read Falling							29*	ns
25	TdXT(DSRR)	XTAL Falling to /DS Read Rising							29*	ns
26	TdXT(DSWF)	XTAL Falling to /DS Write Falling							29*	ns
27	TdXT(DSWF)	XTAL Falling to /DS Write Rising							29*	ns
28	TsW(XT)	Wait Set-up Time							10*	ns
29	ThW(XT)	Wait Hold Time							15*	ns
30	TwW	Wait Width (One Wait Time)							25*	ns

Notes:

When using extended memory timing add 2 TpC.

Timing numbers given are for minimum TpC.

* Preliminary value to be characterized.

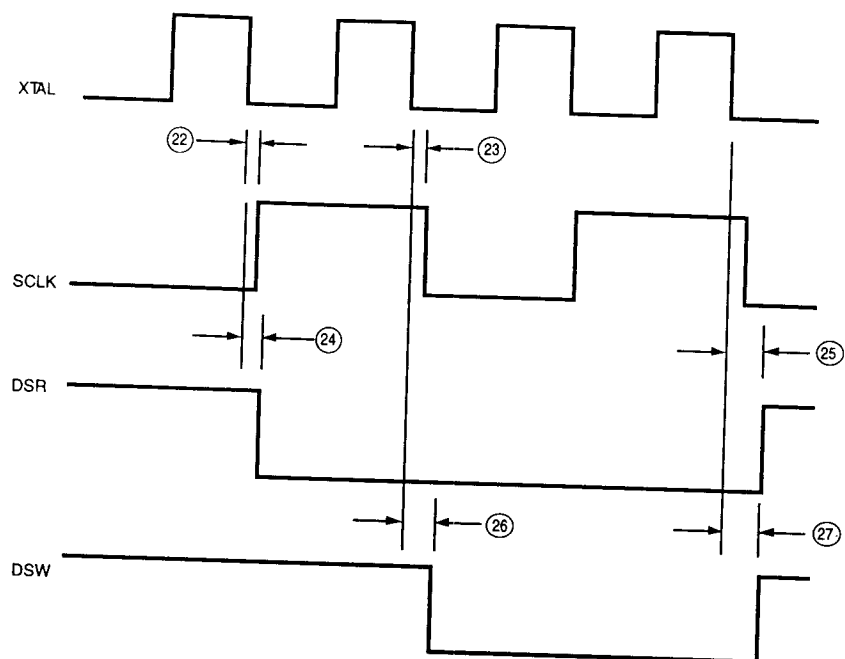


Figure 25. XTAL/SCLK To DSR and DSW Timing

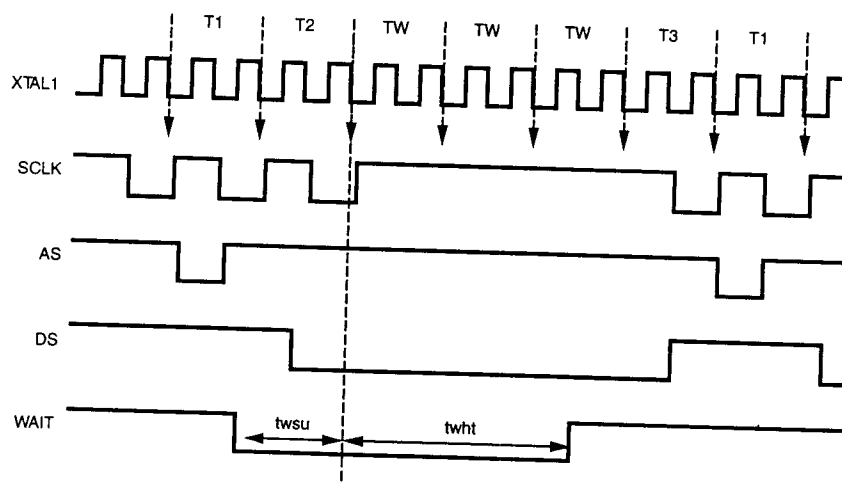


Figure 26. XTAL/SCLK To WAIT Timing
(25 MHz Device Only)

AC CHARACTERISTICS

Additional Timing Diagram

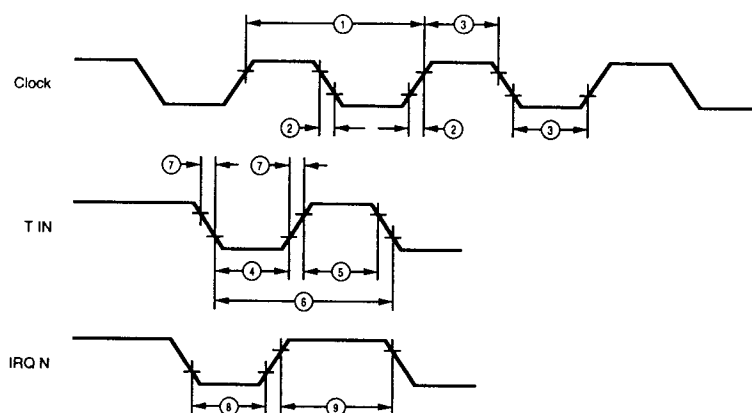


Figure 27. Additional Timing

AC CHARACTERISTICS

Additional Timing Table

No	Symbol	Parameter	T _A = 0°C to +70° C						Units	Notes
			33 MHz		24 MHz		20 MHz			
			Min	Max	Min	Max	Min	Max		
1	TpC	Input Clock Period	30	1000	42	1000	50	1000	ns	[1]
2	TrC,TfC	Clock Input Rise & Fall Times		5		10		10	ns	[1]
3	TwC	Input Clock Width	10		11		15		ns	[1]
4	TwTinL	Timer Input Low Width	75		75		75		ns	[2]
5	TwTinH	Timer Input High Width	3TpC		3TpC		3TpC			[2]
6	TpTin	Timer Input Period	8TpC		8TpC		8TpC			[2]
7	TrTin,TfTin	Timer Input Rise & Fall Times	100		100		100		ns	[2]
8A	TwIL	Interrupt Request Input Low Times	70		70		70		ns	[2,4]
8B	TwIL	Interrupt Request Input Low Times	5TpC		5TpC		5TpC			[2,5]
9	TwIH	Interrupt Request Input High Times	3TpC		3TpC		3TpC			[2,3]

Notes:

- [1] Clock timing references use 3.8V for a logic 1 and 0.8V for a logic 0.
- [2] Timing references use 2.0V for a logic 1 and 0.8V for a logic 0.
- [3] Interrupt references request via Port 3.
- [4] Interrupt request via Port 3 (P31-P33).
- [5] Interrupt request via Port 30.

AC CHARACTERISTICS Handshake Timing Table

No	Symbol	Parameter	T _A = 0°C to +70°C		Units	Data Direction
			Min	Max		
1	TsDI(DAV)	Data In Setup Time to /DAV	0		ns	In
2	ThDI(DAV)	RDY to Data In Hold Time	0		ns	In
3	TwDAV	/DAV Width	40		ns	In
4	TdDAVI(RDYf)	/DAV to RDY Delay		70	ns	In
5	TdDAVI(RDYr)	DAV Rise to RDY Wait Time		40	ns	In
6	TdRDYOr(DAVI)	RDY Rise to DAV Delay	0		ns	In
7	TdDO(DAV)	Data Out to DAV Delay		TpC	ns	Out
8	TdDAVO(RDYI)	/DAV to RDY Delay	0		ns	Out
9	TdRDYI(DAVOr)	RDY to /DAV Rise Delay		70	ns	Out
10	TwRDY	RDY Width	40		ns	Out
11	TdRDYIr(DAVOr)	RDY Rise to DAV Wait Time		40	ns	Out

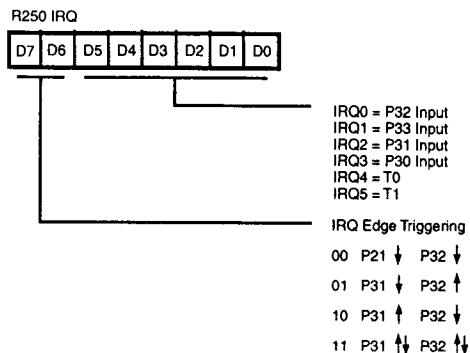


Figure 47. Interrupt Request Register (FAH: Read/Write)

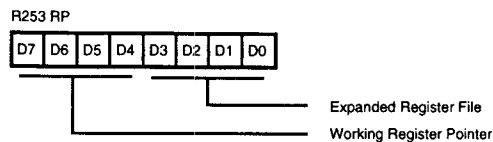


Figure 50. Register Pointer (FDH: Read/Write)

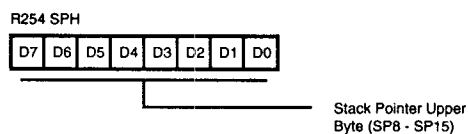


Figure 51. Stack Pointer High (FEH: Read/Write)

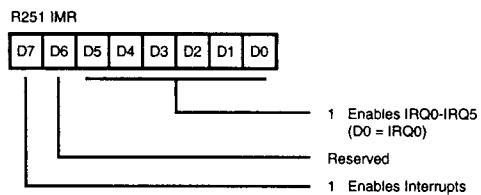


Figure 48. Interrupt Mask Register (FBH: Read/Write)

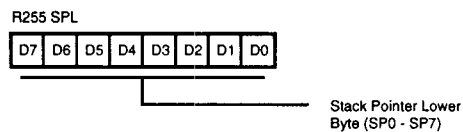


Figure 52. Stack Pointer Low (FFH: Read/Write)

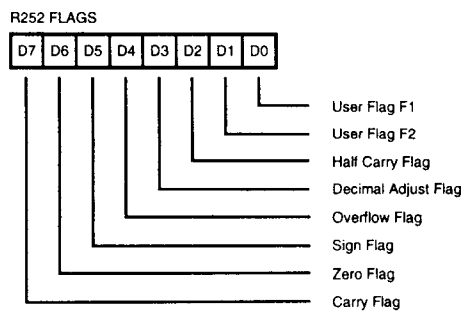


Figure 49. Flag Register (FCH: Read/Write)

INSTRUCTION SET NOTATION

Addressing Modes. The following notation is used to describe the addressing modes and instruction operations as shown in the instruction summary.

Symbol	Meaning
IRR	Indirect register pair or indirect working-register pair address
Irr	Indirect working-register pair only
X	Indexed address
DA	Direct address
RA	Relative address
IM	Immediate
R	Register or working-register address
r	Working-register address only
IR	Indirect-register or indirect working-register address
Ir	Indirect working-register address only
RR	Register pair or working register pair address

Symbols. The following symbols are used in describing the instruction set.

Symbol	Meaning
dst	Destination location or contents
src	Source location or contents
cc	Condition code
@	Indirect address prefix
SP	Stack Pointer
PC	Program Counter
FLAGS	Flag register (Control Register 252)
RP	Register Pointer (R253)
IMR	Interrupt mask register (R251)

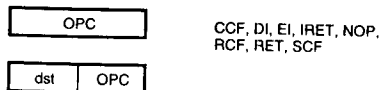
Flags. Control register (R252) contains the following six flags:

Symbol	Meaning
C	Carry flag
Z	Zero flag
S	Sign flag
V	Overflow flag
D	Decimal-adjust flag
H	Half-carry flag

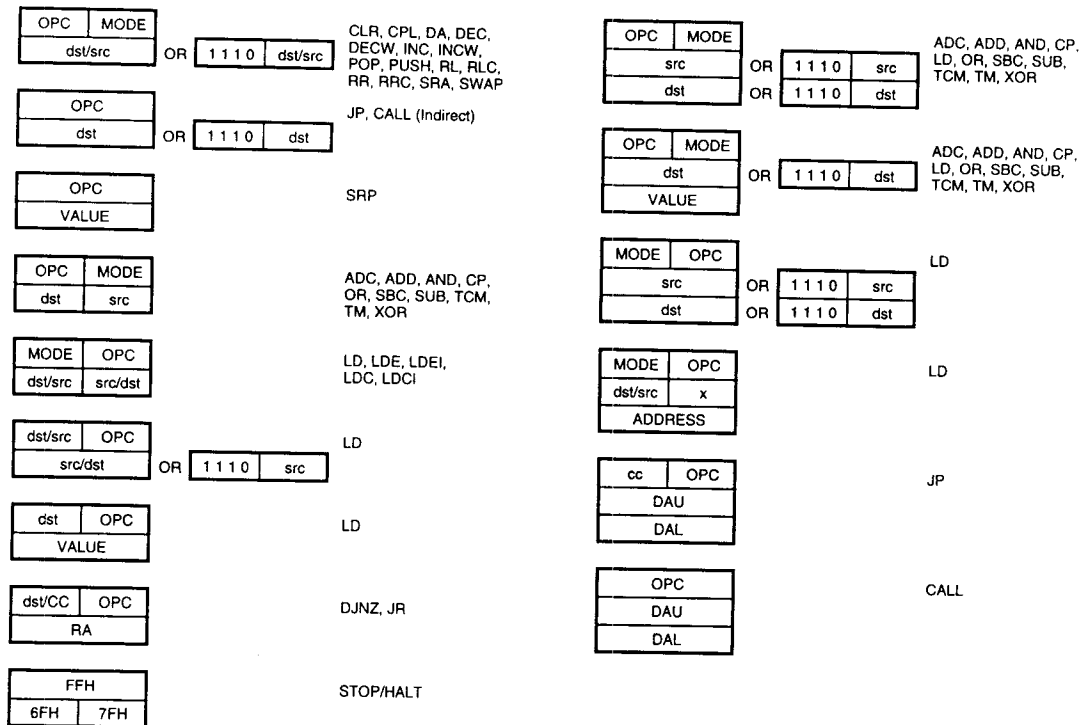
Affected flags are indicated by:

0	Clear to zero
1	Set to one
*	Set to clear according to operation
-	Unaffected
x	Undefined

INSTRUCTION FORMATS



One-Byte Instructions



Two-Byte Instructions

Three-Byte Instructions

INSTRUCTION SUMMARY

Note: Assignment of a value is indicated by the symbol " \leftarrow ". For example:

$$\text{dst} \leftarrow \text{dst} + \text{src}$$

indicates that the source data is added to the destination data and the result is stored in the destination location. The

notation "addr (n)" is used to refer to bit (n) of a given operand location. For example:

$$\text{dst} (7)$$

refers to bit 7 of the destination operand.

INSTRUCTION SUMMARY (Continued)

Instruction and Operation	Address Mode		Opcode Byte (Hex)	Flags Affected						
	dst	src		C	Z	S	V	D	H	
NOP			FF	-	-	-	-	-	-	-
OR dst, src dst ← dst OR src	†		4[]	-	*	*	0	-	-	-
POP dst dst ← @SP; SP ← SP + 1	R		50	-	-	-	-	-	-	-
	IR		51	-	-	-	-	-	-	-
PUSH src SP ← SP - 1; @SP ← src		R	70	-	-	-	-	-	-	-
		IR	71	-	-	-	-	-	-	-
RCF C ← 0			CF	0	-	-	-	-	-	-
RET PC ← @SP; SP ← SP + 2			AF	-	-	-	-	-	-	-
RL dst	R		90	*	*	*	*	-	-	-
	IR		91	*	*	*	*	-	-	-
RLC dst	R		10	*	*	*	*	-	-	-
	IR		11	*	*	*	*	-	-	-
RRC dst	R		E0	*	*	*	*	-	-	-
	IR		E1	*	*	*	*	-	-	-
SBC dst, src dst ← dst ← src ← C	†		3[]	*	*	*	*	1	*	*
SCF C ← 1			DF	1	-	-	-	-	-	-
SRA dst	R		D0	*	*	*	0	-	-	-
	IR		D1	*	*	*	0	-	-	-
SRP src RP ← src		Im	31	-	-	-	-	-	-	-

Instruction and Operation	Address Mode		Opcode Byte (Hex)	Flags Affected						
	dst	src		C	Z	S	V	D	H	
STOP			6F	-	-	-	-	-	-	-
SUB dst, src dst ← dst ← src	†		2[]	*	*	*	*	1	*	*
SWAP dst	R		F0	X	*	*	X	-	-	-
	IR		F1	X	*	*	X	-	-	-
TCM dst, src (NOT dst) AND src	†		6[]	-	*	*	0	-	-	-
TM dst, src dst AND src	†		7[]	-	*	*	0	-	-	-
XOR dst, src dst ← dst XOR src	†		B[]	-	*	*	0	-	-	-

† These instructions have an identical set of addressing modes, which are encoded for brevity. The first opcode nibble is found in the instruction set table above. The second nibble is expressed symbolically by a '[]' in this table, and its value is found in the following table to the left of the applicable addressing mode pair.

For example, the opcode of an ADC instruction using the addressing modes r (destination) and Ir (source) is 13.

Address Mode		Lower Opcode Nibble
dst	src	
r	r	[2]
r	Ir	[3]
R	R	[4]
R	IR	[5]
R	IM	[6]
IR	IM	[7]

Notes:

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